

DESCRIPTION

The SPN7002 is the N-Channel enhancement mode field effect transistors are produced using high cell density DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 300mA DC and can deliver pulsed currents up to 1.0A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

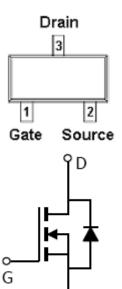
APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- High saturation current capability. Direct Logic-Level Interface: TTL/CMOS
- Battery Operated Systems
- Solid-State Relays

FEATURES

- \bullet 60V/0.50A, RDS(ON)=6.0 Ω (Ω)VGS=10V
- 60V/0.30A, RDS(ON)= 7.0Ω @VGS=5V
- ◆ Super high density cell design for extremely low RDS(ON)
- Exceptional on-resistance and maximum DC current capability
- SOT-23 and SOT-323 package design

PIN CONFIGURATION(SOT-23, SOT-323)



PART MARKING



Y : Year Code W : Week Code

2020/1/20 Ver.5

PIN DESCRIPTION					
Pin	Symbol	Description			
1	G	Gate			
2	S	Source			
3	D	Drain			

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN7002S23RGB	SOT-23	S72
SPN7002S32RGB	SOT-323	S72

% Week Code : A ~ Z(1 ~ 26); a ~ z(27 ~ 52)

※ SPN7002S23RGB: Tape Reel; Pb − Free; Halogen − Free

※ SPN7002S32RGB: Tape Reel; Pb − Free; Halogen − Free

ABSOULTE MAXIMUM RATINGS (Ta=25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage	VDSS	60	V	
Gate –Source Voltage - Continuous	VGSS	±20	V	
Gate –Source Voltage - Non Repetitive (tp	VGSS	±40	V	
Continuous Drain Current(TJ=150°C)	Ta=25°C	ID	0.5	A
Pulsed Drain Current (*)		Ірм	1.0	A
Power Dissipation	Ta=25°C	PD	0.35	W
Operating Junction Temperature		Тл	-55 ~ 150	°C
Storage Temperature Range		Tstg	-55 ~ 150	°C
Thermal Resistance-Junction to Ambient		RөJA	375	°C/W

(*) Pulse width limited by safe operating area

Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit
Static	- J			<i>J</i> F		
	**	V. 0111 050 1		1		T
Drain-Source Breakdown Voltage	V(BR)DSS	VGS=0V,ID=250uA	60			V
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	D=250uA 1.0 1.7		2.5	·
Gate Leakage Current	Igss	$V_{DS}=0V,V_{GS}=\pm20V$			±100	nA
Zero Gate Voltage Drain Current		VDS=48V,VGS=0V			1	uA
	Idss	V _{DS} =48V,V _{GS} =0V T _J =55°C			10	
Drain-Source On-Resistance	RDS(on)	VGS=10V,ID=0.50A VGS=5V,ID=0.30A		2.5	6.0 7.0	Ω
Source-drain Current	Isd				0.35	Α
Source-drain Current (pulsed)	Isdm (2)				1.4	A
Forward Transconductance	Gfs(1)	VDS=10V, ID=0.5 A		0.6		S
Diode Forward Voltage	VsD(1)	Vgs=0V, Is=0.12A		0.85	1.5	V
Dynamic						
Total Gate Charge	Qg	V _{DD} = 30 V, I _D = 1 A, V _{GS} = 5 V		1.4	2.0	nC
Gate-Source Charge	Qgs			0.8		
Gate-Drain Charge	Qgd			0.5		
Input Capacitance	Ciss	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}, $ $V_{GS} = 0$		43	60	pF
Output Capacitance	Coss			20	30	
Reverse Transfer Capacitance	Crss			6	10	
Turn-On Time	td(on)	$V_{DD} = 30 \text{ V, ID} = 0.5 \text{ A}$ $R_{G} = 4.7\Omega \text{ V}_{GS} = 4.5 \text{ V}$		5	20	nS
	tr			15		
Turn-Off Time	td(off)			7	20	
	tf			8		

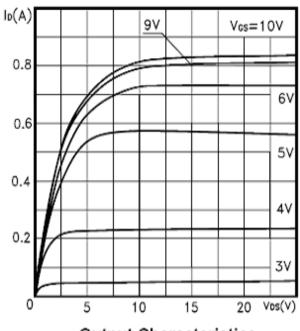
⁽¹⁾ Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

⁽²⁾ Pulse width limited by safe operating area.

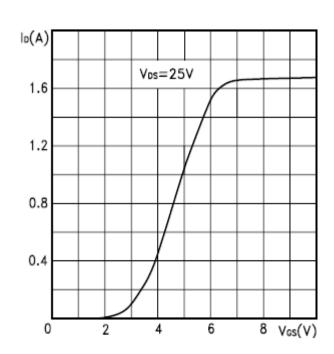


N-Channel Enhancement Mode MOSFET

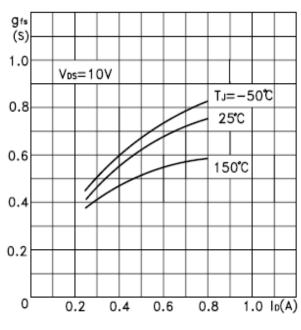
TYPICAL CHARACTERISTICS



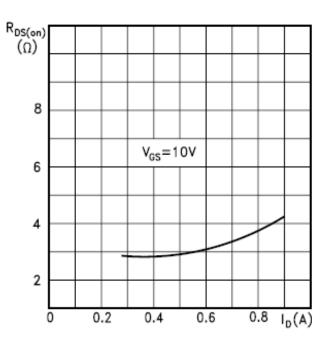
Output Characteristics



Transfer Characteristics



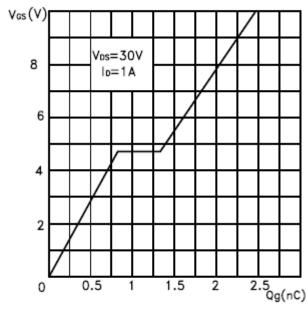
Transconductance



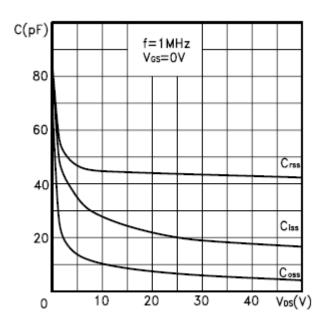
Static Drain-source On Resistance



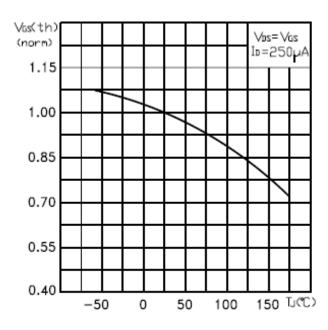
TYPICAL CHARACTERISTICS



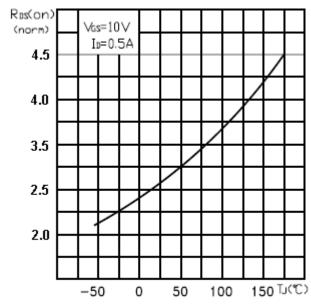
Gate Charge vs Gate-source Voltage



Capacitance Variations



Normalized Gate Threshold Voltage vs Temperature

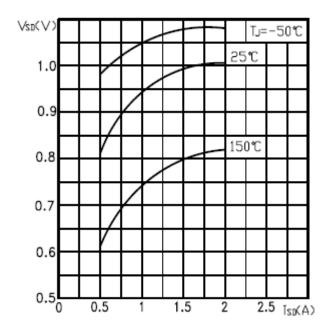


Normalized On Resistance vs Temperature

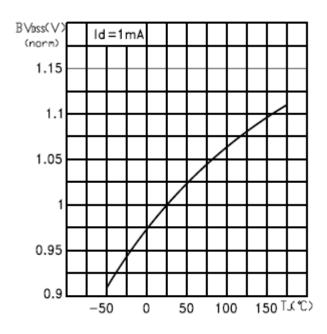


N-Channel Enhancement Mode MOSFET

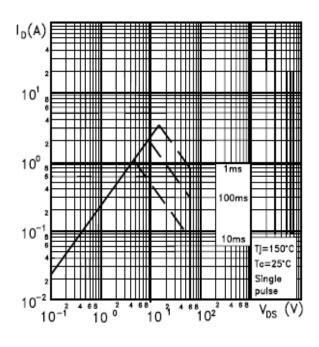
TYPICAL CHARACTERISTICS



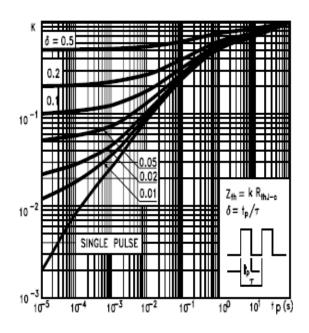
Source-Drain Forward



Normalized BVDSS vs Temperature

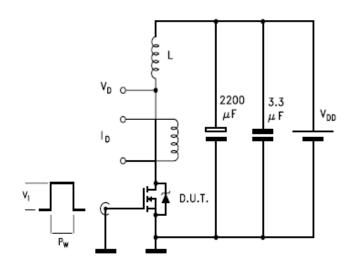


Safe Operating Area



Thermal Impedance

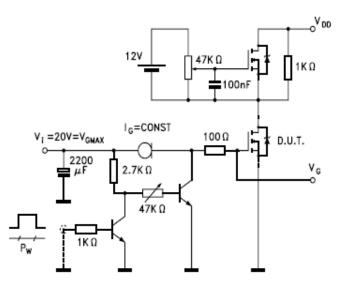
TYPICAL TESTING CIRCUIT



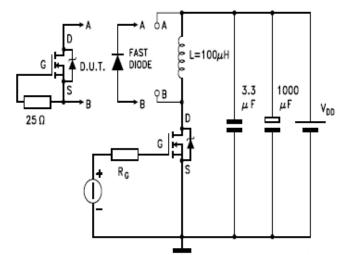
R_L 2200 3.3 μF V_{DD} V_S R_G D.U.T.

Unclamped Inductive Load Test

Switching Times Test Circuit



Gate Charge Test Circuit



Test Circuit For Inductive Load Switching and Diode Recovery Times

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